#### Mechanical Characterization of Interfaces in SOFCs

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> 8th Annual SECA Workshop San Antonio, Texas August 7-9, 2007



## Outline

- Background
- Methodology
- Results
- Future Work



# Background



- Residual Stresses
  - Fabrication
  - Induced by the formation of new phases
  - Changes in porosity (stiffness)
- Interfacial Electrical Resistance



# Methodology

- Physical of Mechanical properties of contact paste
  - Elastic properties, thermal and electrical conductivity, thermal expansion, microstructure, uniaxial and biaxial strength as a function of processing conditions, temperature, time and thermal cycling
- Physical and Mechanical Characterization of contact paste-interconnect interface as a function of time, temperature and thermal cycling.
  - Energy Release Rate
  - Residual Stresses





The mechanical evaluation of thin, porous structures is challenging

We are using Resonant Ultrasound Spectroscopy to determine the elastic properties of LSM contact paste



## **Methodology (Elastic Constants)**



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QuickTime™ and a Microsoft Video 1 decompressor are needed to see this picture.

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#### **Spectra of Coated/Uncoated Specimens**



#### Position of resonant peaks change due to film sintering





• Coated+Sintered Specimen modes have a lower frequency by 0.822 %



#### **Optimization reveals low value of LSM Elastic Modulus**

Optimization was performed using ANSYS<sup>™</sup>

| Iteration # | Range of E for Optimization | Range of v | Optimized E | Optimized v | RMS Error |
|-------------|-----------------------------|------------|-------------|-------------|-----------|
| 1           | 10-50 GPa                   | 0.20-0.40  | 10.00 GPa   | 0.258       | 1.49%     |
| 2           | 0.1-10.0 GPa                | 0.20-0.40  | 1.25 GPa    | 0.39        | 1.39%     |
| 3           | 0.1-10.0 GPa                | 0.25       | 1.28 GPa    | 0.25        | 1.39%     |

The value obtained for the elastic modulus of sintered LSM is low ~ <u>**1.25 GPa**</u> but in the range of values previously reported by Adamson\* (~5 GPa)

\* M. T, Adamson, Ph.D. Thesis, University of London (1997)





## Interfacial Characterization of Cathode Contact Paste Interconnect



# **Sample Preparation**





screen printer

- Crofer22
  - Cut and ground to either 30 or 15 mm in length and 300  $\mu m$  in thickness with high values of flatness and parallelism
- Commercial LSM Paste
  - Applied by screen printing
  - Various thickness values

$$G = \frac{(1 - v^2) M^2}{2E} \left( \frac{1}{I_2} - \frac{1}{I_c} \right)$$

$$\begin{split} M &= Pl/2b\\ I_c &= h_1^3/12 + h_2^3/12 + h_1h_2(h_1 + h_2)/4\\ I_2 &= h_2^3/12\\ I_c &= \frac{2}{3}h_2^3 + \kappa(\frac{1}{12}h_1^3) + h_2^2h_1 + \frac{1}{2}h_1^2h_2\\ \kappa &= \frac{E_1(1 - \nu_2^2)}{E_2(1 - \nu_1^2)} \end{split}$$



Hofinger et al., International Journal of Fracture 92: 213-220, 1998.



#### **Determination of Strain Energy Release Rate**



#### Effect of sintering condition on Interfacial Fracture Toughness of LSM contact paste-Crofer 22





# Sintered at 800°C for 1 hour



Mixed-mode cohesive/adhesive failure



#### Summary

- Techniques have been identified and used to determine the elastic properties of thin porous layers of LSM contact paste materials
- A methodology was established to determine the the fracture toughness of the interface between metallic interconnects and LSM contact paste.
- Fracture toughness was found to increase with sintering temperature and time.



### **Current and Future Work**

- Working with PNNL team to characterize state-of-theart systems
  - Spinel-coated Croffer22
  - Cathode contact paste
- Continue activities to demonstrate feasibility of determining the elastic properties of thin coatings by RUS using well-characterized substrates
- Continue generating data (thermophysical and mechanical properties) to support on-going modeling efforts
- Investigate aging and thermal cycling effects on properties



